

Report NO.: MG00001000091

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAE35P03
Package Type :	DFNWB3x3-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	2.4986%
Lead Frame	Cu	7440-50-8	97.40%	32.3194%
	Fe	7439-89-6	2.40%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.10%	
	Ag	7440-22-4	0.02%	
Epoxy	Silver	7440-22-4	71.00%	1.9011%
	Epoxy resin	proprietary	18.00%	
	Epoxy resin modifier	proprietary	7.00%	
	dapsone	80-08-0	3.00%	
	substituted silane	proprietary	1.00%	
Wire	Cu	7440-50-8	97.00%	0.5432%
	Pd	7440/5/3	3.00%	
Mold Compound	Epoxy Resin1	Trade secret	3.00%	49.4297%
	Epoxy Resin2	Trade secret	3.00%	
	Phenolic Resin	Trade secret	5.00%	
	catalyst	Trade secret	0.50%	
	Carbon Black	1333-86-4	0.30%	
	Amorphous silica 1	60676-86-0	80.00%	
	Amorphous silica 2	7631-86-9	8.20%	
Plating	Tin	7440-31-5	100.00%	13.308%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.